



Spec No.: DS22-2000-284 Effective Date: 11/01/2014

Revision: C

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4

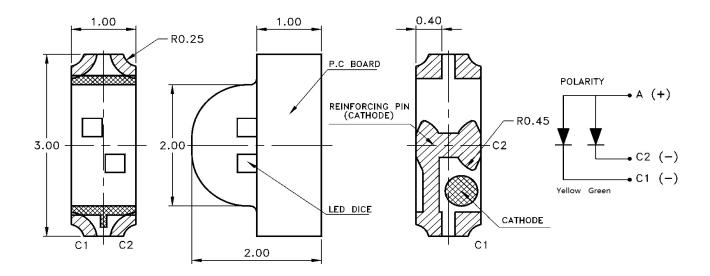


Property of Lite-On Only

Features

- * Meet ROHS.
- * Side Looking / Dual Color Chip LED with Tin Plating.
- * Package in 8mm tape on 7" diameter reels.
- * EIA STD package.
- * I.C. compatible.
- * Compatible with automatic placement equipment.
- * Compatible with infrared reflow solder process.

Package Dimensions



Devices

Part No.	Lens	Source Color	Pin Assignment
LTST-S326GYKT	Water Clear	GaP on GaP Green	C2
	water Clear	GaAsP on GaP Yellow	C1

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.10 mm (.004") unless otherwise noted.

Part No.: LTST-S326GYKT Page: 1 of 12



Property of Lite-On Only

Absolute Maximum Ratings At Ta=25°C

Parameter	LTST-S3	Unit	
Parameter	Green	Yellow	Omt
Power Dissipation	100	60	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	120	80	mA
DC Forward Current	30	20	mA
Reverse Voltage	5	5	V
Operating Temperature Range	-30°C to + 85°C		
Storage Temperature Range	-40°C to + 85°C		
Infrared Soldering Condition	260°C For 10 Seconds		

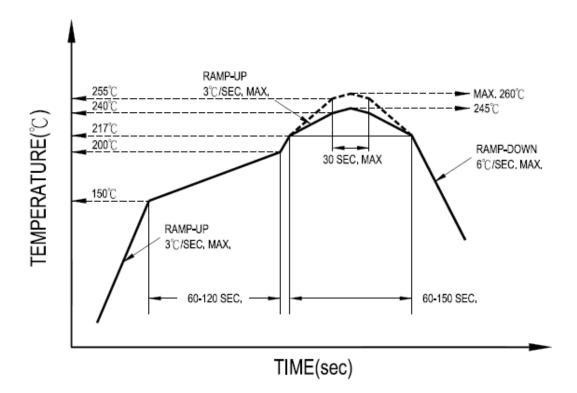
Page: Part No.: LTST-S326GYKT of 12



Property of Lite-On Only



Suggestion IR Reflow Profile For Pb Free Process



Part No.: LTST-S326GYKT Page: 3 of 12



Property of Lite-On Only

Electrical / Optical Characteristics At Ta=25°C

Parameter	Symbol		LTST-S326GYKT		Unit	Test Condition	
Parameter	Symbol		Green	Yellow	Unit	Test Condition	
		MIN.	4.50	1.80			
Luminous Intensity	IV	TYP.	14.0	4.50	mcd	IF =20mA Note 1	
		MAX.	28.0	11.2		1,000 1	
Viewing Angle	201/2	TYP.	130	130	deg	Note 2 (Fig.6)	
Peak Emission Wavelength	λΡ	TYP.	565	585	nm	Measurement @Peak (Fig.1)	
Dominant Wavelength	λd	TYP.	569	588	nm	IF =20mA Note 3	
Spectral Line Half-Width	Δλ	TYP.	30	35	nm		
Earward Voltage	VF	TYP.	2.1	2.1	V	IF =20mA	
Forward Voltage	VΓ	MAX.	2.6	2.6	v	IF =20mA	
Reverse Current	IR	MAX.	10	10	μА	VR = 5V	

Notes: 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.

- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength, λ d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD:

Static Electricity and surge damages the LED. It is recommend to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Part No.: LTST-S326GYKT Page: 4 of 12



Property of Lite-On Only

Bin Code List

Luminous Intensity	Color: Green, Unit: mcd@20mA		
Bin Code	Min.	Max.	
J	4.50	7.10	
K	7.10	11.2	
L	11.2	18.0	
M	18.0	28.0	

Tolerance on each Intensity bin is +/-15%

Luminous Intensity	Color: Yellow, Unit: mcd @20mA		
Bin Code	Min.	Max.	
G	1.80	2.80	
Н	2.80	4.50	
J	4.50	7.10	
K	7.10	11.2	

Tolerance on each Intensity bin is +/-15%

Page: Part No.: LTST-S326GYKT 5 12



Property of Lite-On Only

Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

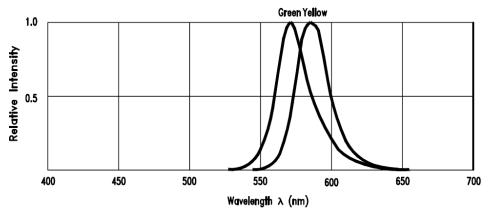


Fig.1 Relative Intensity vs. Wavelength

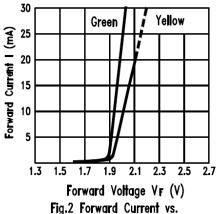
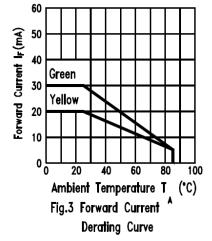


Fig.2 Forward Current vs. Forward Voltage



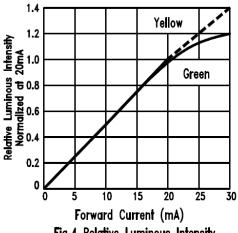


Fig.4 Relative Luminous Intensity vs. Forward Current

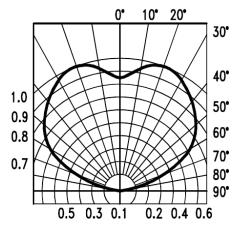


Fig.5 Spatial Distribution

No.: LTST-S326GYKT Page: 12 Part 6 of



Property of Lite-On Only

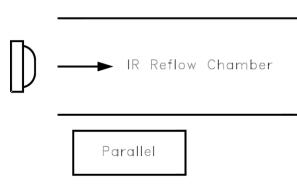
Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package. If clean is necessary, immerse the LED in ethyl alcohol or in isopropyl alcohol at normal temperature for less one minute.

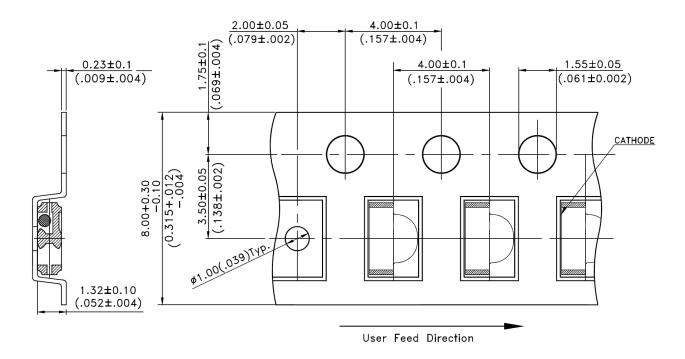
Suggest Soldering Pad Dimensions

0.90 C1 5.00 2.00 0.90 Luminous Direction C2 Anode

Suggest Soldering direction:



Package Dimensions Of Tape And Reel

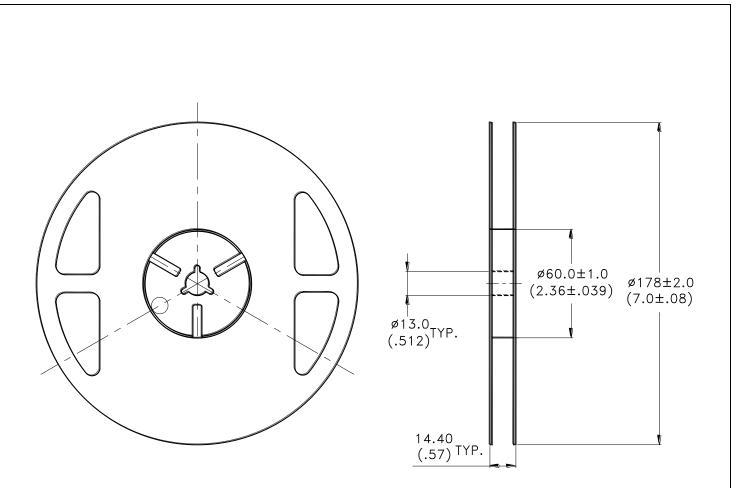


Notes:

1. All dimensions are in millimeters (inches).



Property of Lite-On Only



Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 7 inch reel-3000 pieces per reel.
- 3. Minimum packing quantity is 500 pcs for remainders.
- 4. The maximum number of consecutive missing lamps is two.
- 5. In accordance with ANSI/EIA 481 specifications.

Part No.: LTST-S326GYKT Page: 8 of 12



Property of Lite-On Only

CAUTIONS

1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. Storage

he package is sealed:

The LEDs should be stored at $30 \,^{\circ}$ C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

The package is opened:

The storage ambient for the LEDs should not exceed 30 °C temperature or 60% relative humidity.

It is recommended that LEDs out of their original packaging are IR-reflowed within one week.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant, or in a desiccators with nitrogen ambient.

LEDs stored out of their original packaging for more than one week should be baked at about 60 deg C for at least 20 hours before solder assembly.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

4. Soldering

Recommended soldering conditions:

Reflow soldering		Wave Soldering		Soldering iron	
Pre-heat	120~150 ℃	Pre-heat	100 ℃ Max.	Temperature	300 ℃ Max.
Pre-heat time	120 sec. Max.	Pre-heat time	60 sec. Max.	Soldering time	3 sec. Max.
Peak temperature	240 ℃ Max.	Solder wave	260 ℃ Max.		(one time only)
Soldering time	10 sec. Max.	Soldering time	10 sec. Max.		

Soldering notes:

Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.

However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

LITE-ON Runs both component-level verification using in-house **KYRAMX98** reflow chambers and board-level assembly.

The results of this testing are verified through post-reflow reliability testing.

Profiles used at LITE-ON are based on JEDEC standards to ensure that all packages can be successfully and reliably surface mounted.

Figure on page3 shows a sample temperature profile compliant to JEDEC standards.

You can use this example as a generic target to set up your reflow process.

You should adhere to the JEDEC profile limits as well as specifications and recommendations from the solder paste manufacturer to avoid damaging the device and create a reliable solder joint.

Part No.: LTST-S326GYKT	Page:	9	of	12	
-------------------------	-------	---	----	----	--



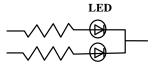
Property of Lite-On Only

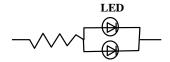
5. Drive Method

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

Circuit model A

Circuit model B





- (A) Recommended circuit.
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

6. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents.

To verify for ESD damage, check for "lightup" and Vf of the suspect LEDs at low currents. The Vf of "good" LEDs should be >2.0 V @ 0.1 mA for InGaN product and >1.4 V @ 0.1 mA for AlInGaP product.

Part No.: LTST-S326GYKT Page: 10 of 12



Property of Lite-On Only

7. Reliability Test

Classification	Test Item	Test Condition	Reference Standard
	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
Endurance Test	High Temperature High Humidity Storage	IR-Reflow In-Board, 2 Times $Ta=65\pm5^{\circ}\text{C}$, RH= 90 \sim 95% *Test Time= 240HRS \pm 2HRS	MIL-STD-202F:103B JIS C 7021:B-11
1550	High Temperature Storage	Ta= 105 ±5 °C *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-883D:1008 JIS C 7021:B-10
	Low Temperature Storage	Ta= -55±5°C *Test Time=1000HRS (-24HRS,+72H RS)	JIS C 7021:B-12
	Temperature Cycling	$105^{\circ}\text{C} \sim 25^{\circ}\text{C} \sim -55^{\circ}\text{C} \sim 25^{\circ}\text{C}$ 30mins 5mins 30mins 5mins 10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS C 7021:A-4
	Thermal Shock	IR-Reflow In-Board, 2 Times $85 \pm 5^{\circ}$ C $\sim -40^{\circ}$ C $\pm 5^{\circ}$ C 10mins 10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
Environmental	Solder Resistance	T.sol= $260 \pm 5^{\circ}$ C Dwell Time= 10 ± 1 secs	MIL-STD-202F:210A MIL-STD-750D:2031 JIS C 7021:A-1
Test	IR-Reflow Pb Free Process	Ramp-up rate(217°C to Peak) $+3$ °C/ second max Temp. maintain at $175(\pm 25)$ °C 180 seconds max Temp. maintain above 217 °C 60-150 seconds Peak temperature range 260 °C+0/-5°C Time within 5°C of actual Peak Temperature (tp) 20-40 seconds Ramp-down rate $+6$ °C/second max	MIL-STD-750D:2031.2 J-STD-020C
	Solderability	T.sol= $235 \pm 5^{\circ}$ C Immersion time 2 ± 0.5 sec Immersion rate 25 ± 2.5 mm/sec Coverage $\geq 95\%$ of the dipped surface	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20 JIS C 7021:A-2

8. Others

The appearance and specifications of the product may be modified for improvement without prior notice.

Part No.: LTST-S326GYKT Page: 11 of 12



Property of Lite-On Only

9. Suggested Checking List

Training and Certification

- 1. Everyone working in a static-safe area is ESD-certified?
- 2. Training records kept and re-certification dates monitored?

Static-Safe Workstation & Work Areas

- 1. Static-safe workstation or work-areas have ESD signs?
- 2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
- 3. All ionizer activated, positioned towards the units?
- 4. Each work surface mats grounding is good?

Personnel Grounding

- 1. Every person (including visitors) handling ESD sensitive (ESDS) items wears wrist strap, heel strap or conductive shoes with conductive flooring?
- 2. If conductive footwear used, conductive flooring also present where operator stand or walk?
- 3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?
- 4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
- 5. All wrist strap or heel strap checkers calibration up to date? Note: *50V for Blue LED.

Device Handling

- 1. Every ESDS items identified by EIA-471 labels on item or packaging?
- 2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
- 3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
- 4. All flexible conductive and dissipative package materials inspected before reuse or recycles?

Others

- 1. Audit result reported to entity ESD control coordinator?
- 2. Corrective action from previous audits completed?
- 3. Are audit records complete and on file?

Part No.: LTST-S326GYKT Page: 12 of 12

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Lite-On:

LTST-S326GYKT

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

многоканальный

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9